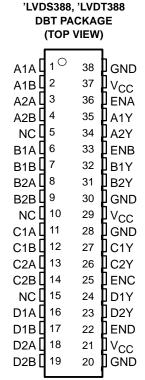
SLLS448A - SEPTEMBER 2000 - REVISED MAY 2001

- Eight Line Receivers Meet or Exceed the Requirements of ANSI TIA/EIA-644 **Standard**
- Integrated 110- Ω Line Termination **Resistors on LVDT Products**
- Designed for Signaling Rates[†] Up To **630 Mbps**
- **SN65 Version's Bus-Terminal ESD Exceeds**
- **Operates From a Single 3.3-V Supply**
- Propagation Delay Time of 2.6 ns (Typ)
- Output Skew 100 ps (Typ) Part-To-Part Skew Is Less Than 1 ns
- **LVTTL Levels Are 5-V Tolerant**
- **Open-Circuit Fail Safe**
- Flow-Through Pin Out
- Packaged in Thin Shrink Small-Outline Package With 20-mil Terminal Pitch

description

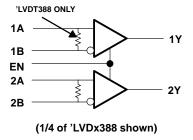
The 'LVDS388 and 'LVDT388 (T designates integrated termination) are eight differential line receivers that implement the electrical characteristics of low-voltage differential signaling (LVDS). This signaling technique lowers the output voltage levels of 5-V differential standard levels (such as EIA/TIA-422B) to reduce the power, increase the switching speeds, and allow operation with a 3-V supply rail. Any of the eight differential receivers will provide a valid logical output state with a +100-mV differential input voltage within the input common-mode voltage range. The input common-mode voltage range allows 1 V of ground potential difference between two LVDS nodes. Additionally, the high-speed switching of LVDS signals always require the use of a line impedance matching resistor at the receiving end of the cable or transmission media. The LVDT product eliminates this external resistor by integrating it with the receiver.

NOT RECOMMENDED FOR NEW DESIGNS For Replacement Use 'LVDx388A



logic diagram (positive logic)

'LVDx388





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

† Signaling rate, 1/t, where t is the minimum unit interval and is expressed in the units bits/s (bits per second)



SN65LVDS388, SN65LVDT388, SN75LVDS388, SN75LVDT388 HIGH-SPEED DIFFERENTIAL LINE RECEIVERS

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description (continued)

The intended application of this device and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately $100\,\Omega$. The transmission media may be printed-circuit board traces, backplanes, or cables. The large number of drivers integrated into the same substrate along with the low pulse skew of balanced signaling, allows extremely precise timing alignment of clock and data for synchronous parallel data transfers. When used with its companion, 8-channel driver, the SN65LVDS389 over 150 million data transfers per second in single-edge clocked systems are possible with very little power. Note: The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other system characteristics.

The SN65LVDS388 and SN65LVDT388 is characterized for operation from –40°C to 85°C. The SN75LVDS388 and SN75LVDT388 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

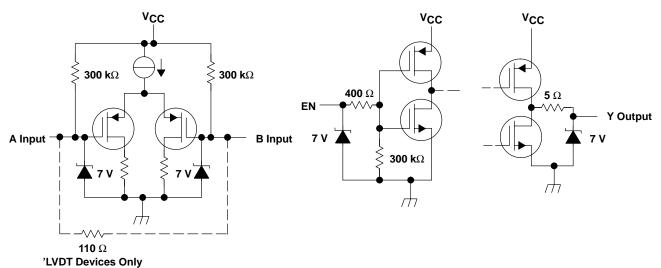
PART NUMBER	TEMPERATURE RANGE	NUMBER OF RECEIVERS	BUS-PIN ESD
SN65LVDS388DBT	–40°C to 85°C	8	15 kV
SN65LVDT388DBT	–40°C to 85°C	8	15 kV
SN75LVDS388DBT	0°C to 70°C	8	4 kV
SN75LVDT388DBT	0°C to 70°C	8	4 kV

Function Table SNx5LVD388 and SNx5LVDT388

DIFFERENTIAL INPUT	ENABLES	OUTPUT
A-B	EN	Y
V _{ID} ≥ 100 mV	Н	Н
-100 mV < V _{ID} ≤ 100 mV	Н	?
V _{ID} ≤ -100 mV	Н	L
X	L	Z
Open	Н	Н

H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

equivalent input and output schematic diagrams





SN65LVDS388, SN65LVDT388, SN75LVDS388, SN75LVDT388 HIGH-SPEED DIFFERENTIAL LINE RECEIVERS

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage ran	ge, V _{CC} (see Note 1)	0.5 V to 4 V
Voltage range:	Enables or Y	0.5 V to 6 V
	A or B	0.5 V to 4 V
Electrostatic discha	arge: (see Note 2)	
	SN65' (A, B, and GND)	Class 3, A:15 kV, B: 700 V
	SN75' (A, B, and GND)	Class 2, A:4 kV, B: 400 V
Continuous power	dissipation	See Dissipation Rating Table
Storage temperatu	re range	–65°C to 150°C
Lead temperature	1,6 mm (1/16 in) from case for 10 sec	onds 260°C

NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	T_A ≤ 25°C	DERATING FACTOR [‡]	T _A = 70°C	T _A = 85°C
	1071 mW	ABOVE T _A = 25°C	POWER RATING	POWER RATING
DBT	1071 mW	8.5 mW/°C	688 mW	556 mW

[‡]This is the inverse of the junction-to-ambient thermal resistance when board-mounted (low-k) and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		3	3.3	3.6	V
High-level input voltage, VIH	Enables	2			V
Low-level input voltage, V _{IL}	Enables			0.8	٧
Magnitude of differential input voltage, V _{ID}		0.1		0.6	٧
Common-mode input voltage, V _{IC} (see Figure 4)		$\frac{ V_{\text{ID}} }{2}$	2	$.4 - \frac{ V_{ID} }{2}$	٧
			,	V _{CC} – 0.8	
Operating free-air temperature, T _Δ	SN75'	0		70	°C
operating nee-all temperature, 1 _A	SN65'	-40		85	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} Tested in accordance with MIL-STD-883C Method 3015.7.

SN65LVDS388, SN65LVDT388, SN75LVDS388, SN75LVDT388 HIGH-SPEED DIFFERENTIAL LINE RECEIVERS

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electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CO	NDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going differential input voltage three	shold	Soo Figure 1 on	d Toble 1			100	mV
V _{IT} _	Negative-going differential input voltage three	eshold	See Figure 1 an	See Figure 1 and Table 1				mV
Vон	High-level output voltage		$I_{OH} = -8 \text{ mA}$		2.4	3		V
VOL	Low-level output voltage		IOL = 8 mA			0.2	0.4	V
la a	Supply ourrent		Enabled,	No load		50	70	mA
Icc	Supply current		Disabled				3	mA
		31.VDC	V _I = 0 V			-13	-20	
l	land compat (A an B innuts)	'LVDS			-1.2	-3		4
1	Input current (A or B inputs)	21.VDT	V _I = 0 V, other in			-40	μΑ	
		'LVDT	V _I = 2.4 V, other input open		-2.4			
I _{ID}	Differential input current IIA – IIB	'LVDS		V _{IB} = 0.1 V, V _{IB} = 2.3 V			±2	μΑ
I _{ID}	Differential input current (I _{IA} – I _{IB})	'LVDT	V _{IA} = 0.2 V, V _{IA} = 2.4 V,	V _{IB} = 0 V, V _{IB} = 2.2 V	1.5		2.2	mA
I _I (OFF)	Power-off input current (A or B inputs)	'LVDS	V _{CC} = 0 V,	V _I = 2.4 V		12	±20	μΑ
I _I (OFF)	Power-off input current (A or B inputs)	'LVDT	V _C C = 0 V,	V _I = 2.4 V			±40	μΑ
ΊΗ	High-level input current (enables)	•	V _{IH} = 2 V				10	μΑ
I _Ι L	Low-level input current (enables)		V _{IL} = 0.8 V				10	μΑ
	High important autout autout						±1	4
loz	High-impedance output current		V _O = 3.6 V				10	μΑ
CIN	Input capacitance, A or B input to GND		V _{ID} = 0.4 sin 2.	V _{ID} = 0.4 sin 2.5E09 t V		5		pF
Z _(t)	Termination impedance		$V_{ID} = 0.4 \sin 2.5$	5E09 t V	88		132	Ω

[†] All typical values are at 25°C and with a 3.3-V supply.

switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output		1	2.6	4	ns
tPHL	Propagation delay time, high-to-low-level output		1	2.5	4	ns
t _r	Output signal rise time		500	800	1200	ps
tf	Output signal fall time	See Figure 2	500	800	1200	ps
t _{sk(p)}	Pulse skew (tpHL - tpLH)			150	600	ps
t _{sk(o)}	Output skew [‡]			100	400	ps
tsk(pp)	Part-to-part skew§				1	ns
tPZH	Propagation delay time, high-impedance-to-high-level output			7	15	ns
tPZL	Propagation delay time, high-impedance-to-low-level output	Con Figure 2		7	15	ns
tPHZ	Propagation delay time, high-level-to-high-impedance output	See Figure 3		7	15	ns
tPLZ	Propagation delay time, low-level-to-high-impedance output			7	15	ns

[†] All typical values are at 25°C and with a 3.3-V supply.



[‡] t_{sk(0)} is the magnitude of the time difference between the t_{PLH} or t_{PHL} of all drivers of a single device with all of their inputs connected together. § t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of any two devices characterized in this data sheet when both devices operate with the same supply voltage, at the same temperature, and have the same test circuits.

PARAMETER MEASUREMENT INFORMATION

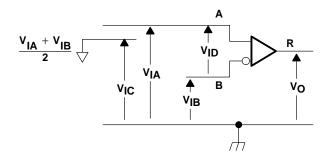
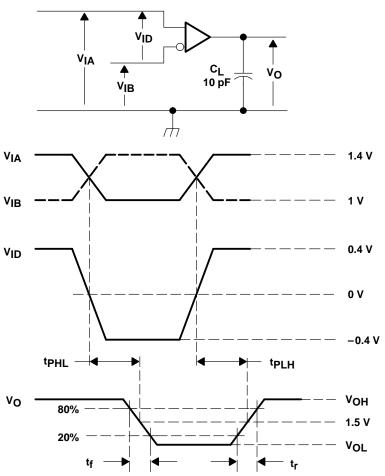


Figure 1. Voltage Definitions

Table 1. Receiver Minimum and Maximum Input Threshold Test Voltages

APPLIED VO	OLTAGES	RESULTING DIFFERENTIAL INPUT VOLTAGE	RESULTING COMMON- MODE INPUT VOLTAGE
VIA	V _{IB}	V _{ID}	VIC
1.25 V	1.15 V	100 mV	1.2 V
1.15 V	1.25 V	−100 mV	1.2 V
2.4 V	2.3 V	100 mV	2.35 V
2.3 V	2.4 V	–100 mV	2.35 V
0.1 V	0 V	100 mV	0.05 V
0 V	0.1 V	–100 mV	0.05 V
1.5 V	0.9 V	600 mV	1.2 V
0.9 V	1.5 V	−600 mV	1.2 V
2.4 V	1.8 V	600 mV	2.1 V
1.8 V	2.4 V	−600 mV	2.1 V
0.6 V	0 V	600 mV	0.3 V
0 V	0.6 V	−600 mV	0.3 V

PARAMETER MEASUREMENT INFORMATION

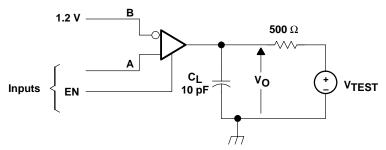


NOTE: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

Figure 2. Timing Test Circuit and Wave Forms



PARAMETER MEASUREMENT INFORMATION



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

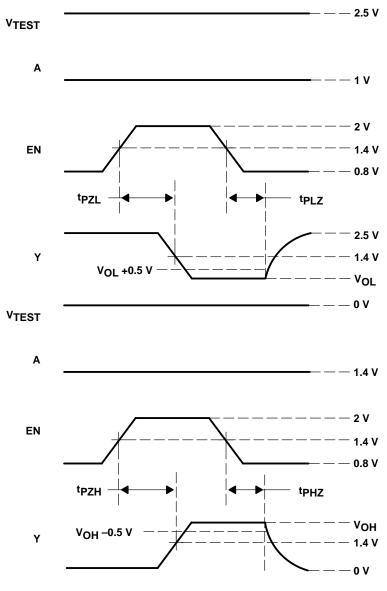
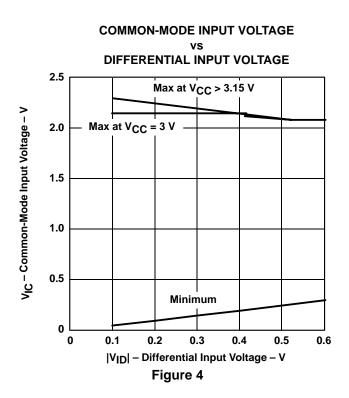
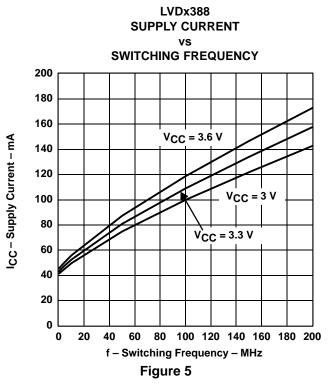
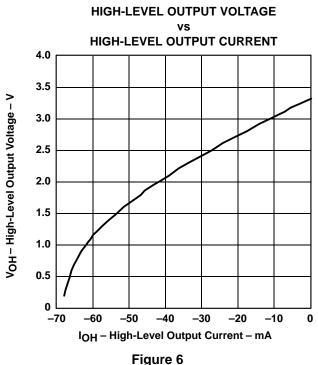


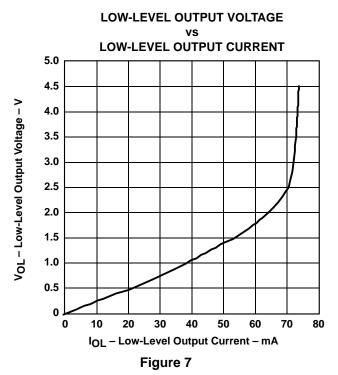
Figure 3. Enable/Disable Time Test Circuit and Wave Forms

TYPICAL CHARACTERISTICS









HIGH-TO-LOW PROPAGATION DELAY TIME

TYPICAL CHARACTERISTICS

LOW-TO-HIGH PROPAGATION DELAY TIME VS FREE-AIR TEMPERATURE 3.0 2.9 2.8 2.7 2.6 2.5 2.4 VCC = 3.6 V VCC = 3.3 V 2.2 2.1

^t PLH – Low-To-High Propagation Delay Time – ns

-50

-30

-10

Figure 8

Ta - Free-Air Temperature - °C

10

30

50

70

90

FREE-AIR TEMPERATURE 3.0 ^t PHL – High-To-Low Propagation Delay Time – ns 2.9 2.8 2.7 2.6 2.5 $V_{CC} = 3 V$ $V_{CC} = 3.6 V$ 2.4 2.3 2.2 V_{CC} = 3.3 V 2.1 -50 -30 -10 50 70 90

T_A – Free-Air Temperature – °C Figure 9

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APPLICATION INFORMATION

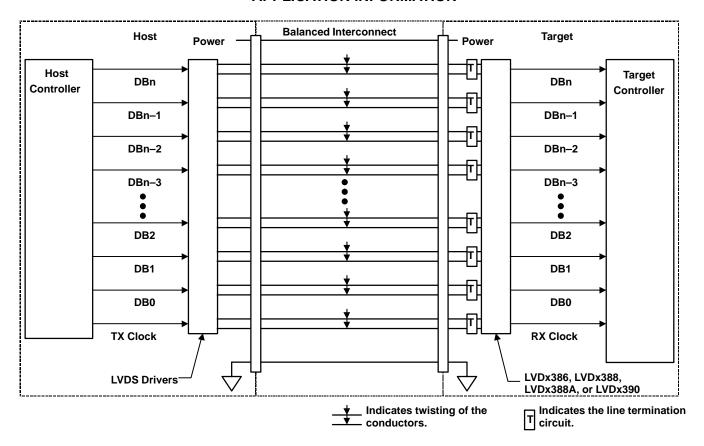


Figure 10. Typical Application Schematic



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APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –100 mV and 100 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different in how it handles the open-input circuit situation, however.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near V_{CC} through 300-k Ω resistors as shown in Figure 10. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.

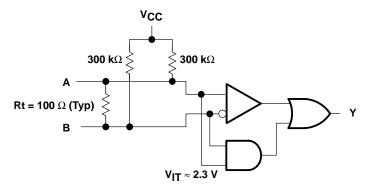


Figure 11. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver will be valid with less than a 100-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.





1-Oct-2011

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN65LVDT388DBT	NRND	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
SN65LVDT388DBTG4	NRND	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
SN65LVDT388DBTR	NRND	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDT388DBTR	TSSOP	DBT	38	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing Pins SF		SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDT388DBTR	TSSOP	DBT	38	2000	367.0	367.0	38.0

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